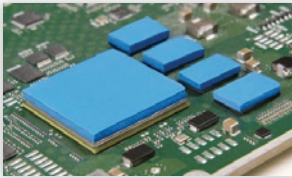


Thermal Solutions for Power Supplies

GAP PAD®



- An effective thermal interface between metal module housing and components where air gaps and rough surface textures are present.

GAP FILLER and LIQUI FORM



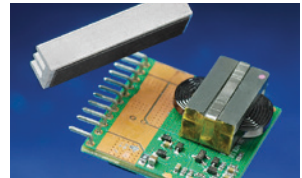
- Low stress liquid material for interfacing fragile components with high topography to metal module housing.
- 2K and 1K versions available.

Phase Change Material



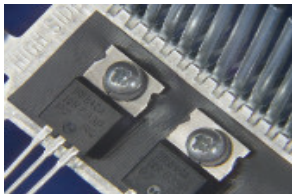
- Material changes from solid to liquid at certain temperatures.
- Outstanding thermal impedance between components and metal module housing.

LIQUI BOND



- Excellent wet out and thermal performance that also acts as a structural adhesive, removing the need for clips and other expensive hardware.

SIL PAD®



- An effective thermal interface between metal module housing and components.
- Provides a robust dielectric interface to help meet safety agency requirements.

BOND PLY



- SIL PAD® with a structural adhesive applied to it that provides proven thermal and dielectric performance while eliminating the need for clips and screw to attach discrete components to a heat sink or rail.

TCLAD



- Thermally conductive printed circuit board (PCB) with wider range of constructions available to meet thermal requirements. Safety agency certified solutions provide excellent heat transfer for surface mount power components.

IsoEdge Heatplate



- Provides a safety agency approved insulation while providing excellent robustness and thermal performance.
- Allows for very small clearances between high voltage components on the board and the heat spreader.